

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ max	$I_D$ $T_A = +25^\circ\text{C}$
12V	$0.15\Omega @ V_{GS} = 4.5\text{V}$	1.41A
	$0.185\Omega @ V_{GS} = 2.5\text{V}$	1.25A
	$0.21\Omega @ V_{GS} = 1.8\text{V}$	1.16A

## Description

This new generation MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.


## Applications

- DC-DC Converters
- Power management functions

## Features

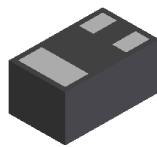
- Low On-Resistance
- Very Low Gate Threshold Voltage  $V_{GS(TH)}$ , 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

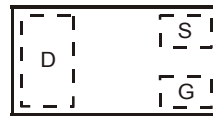
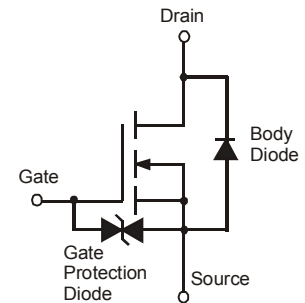
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 
- Weight: 0.001 grams (approximate)



X1-DFN1006-3



Bottom View


 Top View  
 Internal Schematic


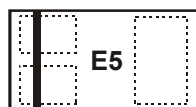
Equivalent Circuit

## Ordering Information (Note 4)

Part Number	Case	Packaging
DMN1150UFB-7B	X1-DFN1006-3	10,000/Tape & Reel

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  - See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  - For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



Top View

E5 = Product Type Marking Code  
 Bar Denotes Gate and Source Side

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V <sub>DSS</sub>	12	V
Gate-Source Voltage			V <sub>GSS</sub>	±6	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	T <sub>A</sub> = +25°C	I <sub>D</sub>	1.41	A
		T <sub>A</sub> = +70°C		1.15	
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I <sub>DM</sub>	7	A
Maximum Body Diode continuous Current			I <sub>S</sub>	1	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	P <sub>D</sub>	0.5	W
	T <sub>A</sub> = +70°C		0.3	
Thermal Resistance, Junction to Ambient (Note 5)		R <sub>θJA</sub>	251	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	12	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	—	—	100	nA	V <sub>DS</sub> = 12V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±1	μA	V <sub>GS</sub> = ±6V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.35	—	1.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	—	—	150	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 1A
			—	185		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 1A
			—	210		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 1A
Diode Forward Voltage	V <sub>SD</sub>	—	0.7	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 150mA
<b>DYNAMIC CHARACTERISTICS (Note 7)</b>						
Input Capacitance	C <sub>iss</sub>	—	106	—	pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	23	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	21	—	pF	
Gate resistance	R <sub>g</sub>	—	92.4	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1.0MHz
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Q <sub>g</sub>	—	1.5	—	nC	V <sub>DS</sub> = 4V, I <sub>D</sub> = 1A
Gate-Source Charge	Q <sub>gs</sub>	—	0.2	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	0.2	—	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	—	4.1	—	ns	V <sub>DD</sub> = 4V, V <sub>GS</sub> = 6V, I <sub>D</sub> = 1A R <sub>G</sub> = 1Ω
Turn-On Rise Time	t <sub>r</sub>	—	34.5	—	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	—	57	—	ns	
Turn-Off Fall Time	t <sub>f</sub>	—	30	—	ns	

- Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.  
 6. Short duration pulse test used to minimize self-heating effect.  
 7. Guaranteed by design. Not subject to product testing.

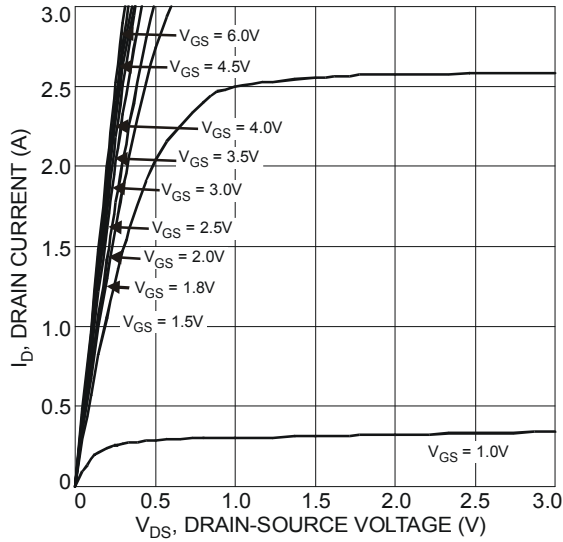


Figure 1 Typical Output Characteristic

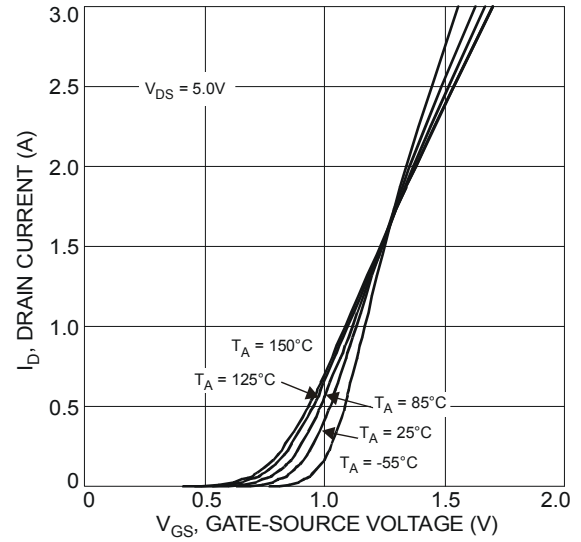


Figure 2 Typical Transfer Characteristics

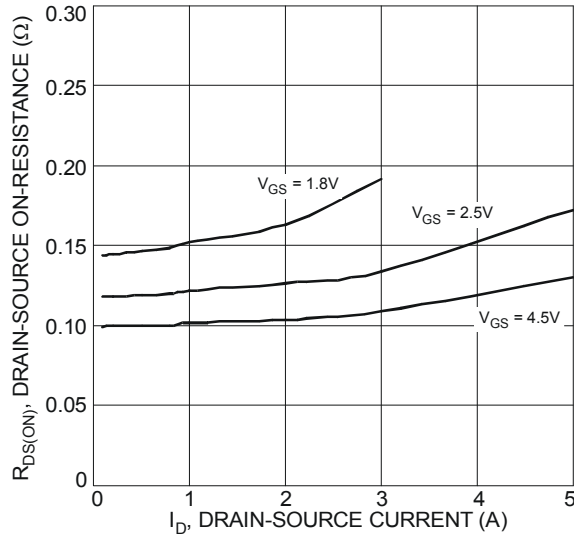


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

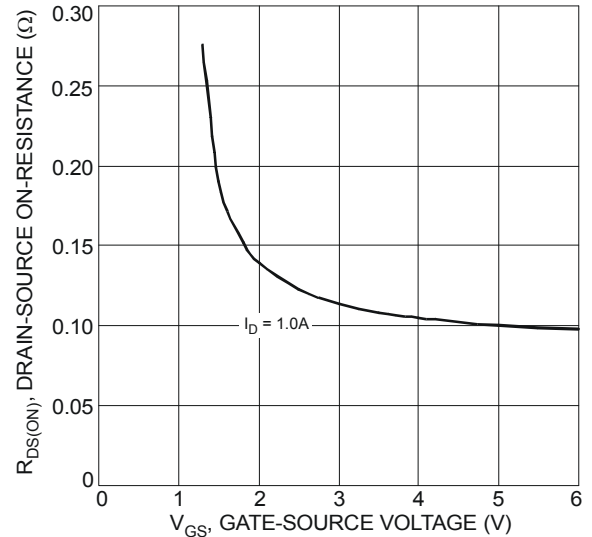


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

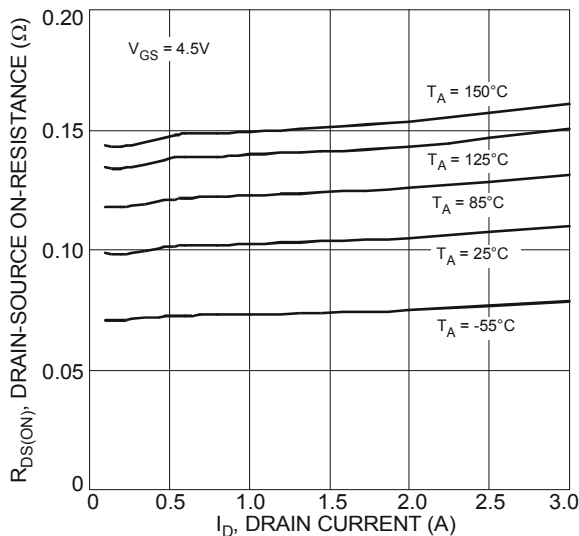


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

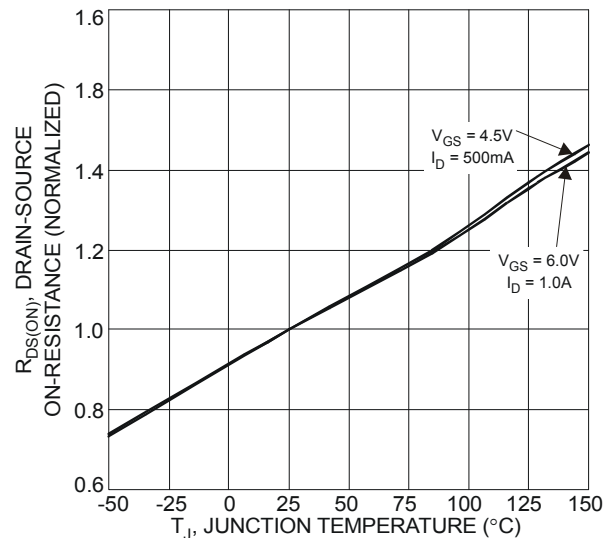
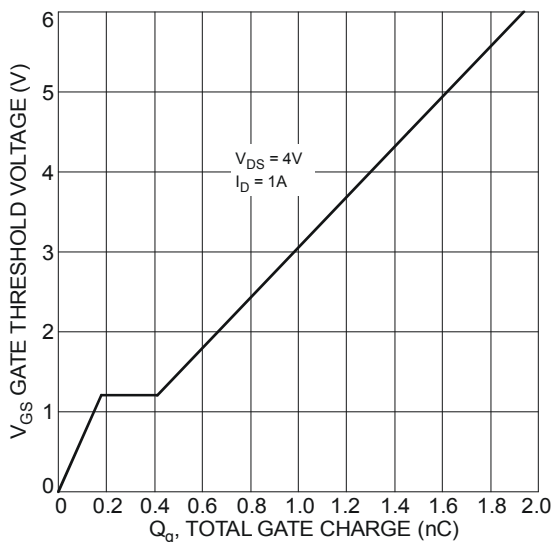
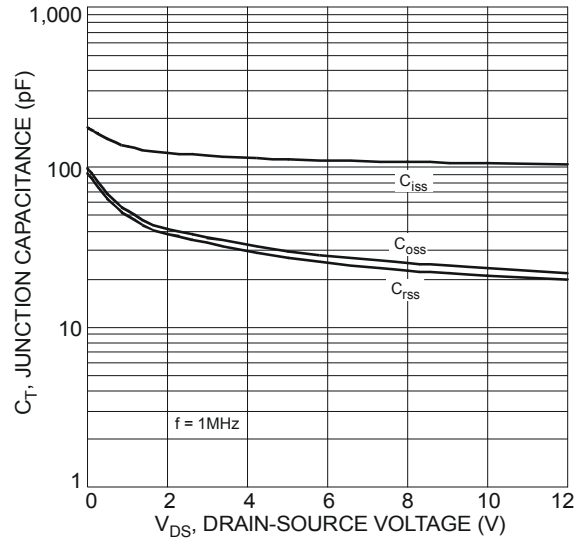
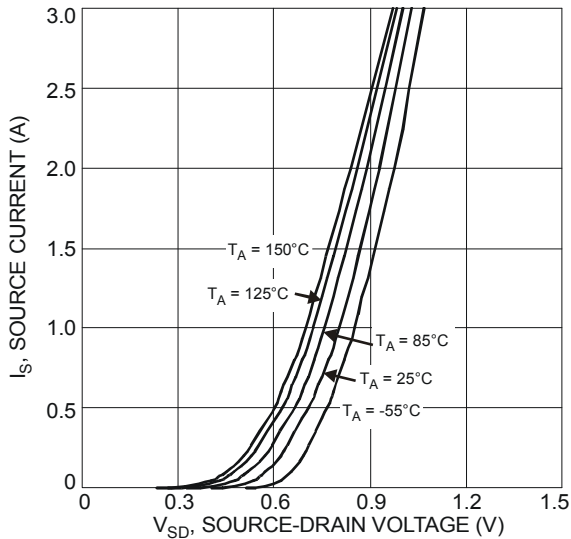
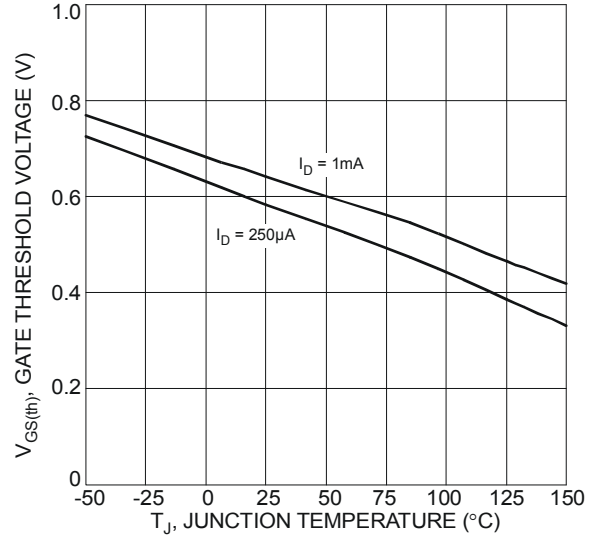
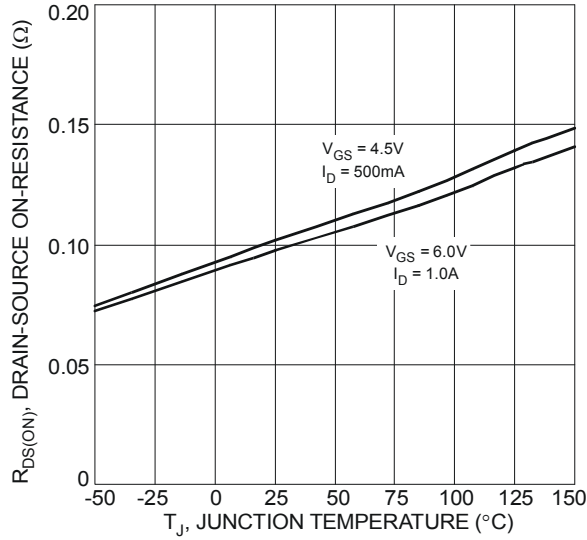
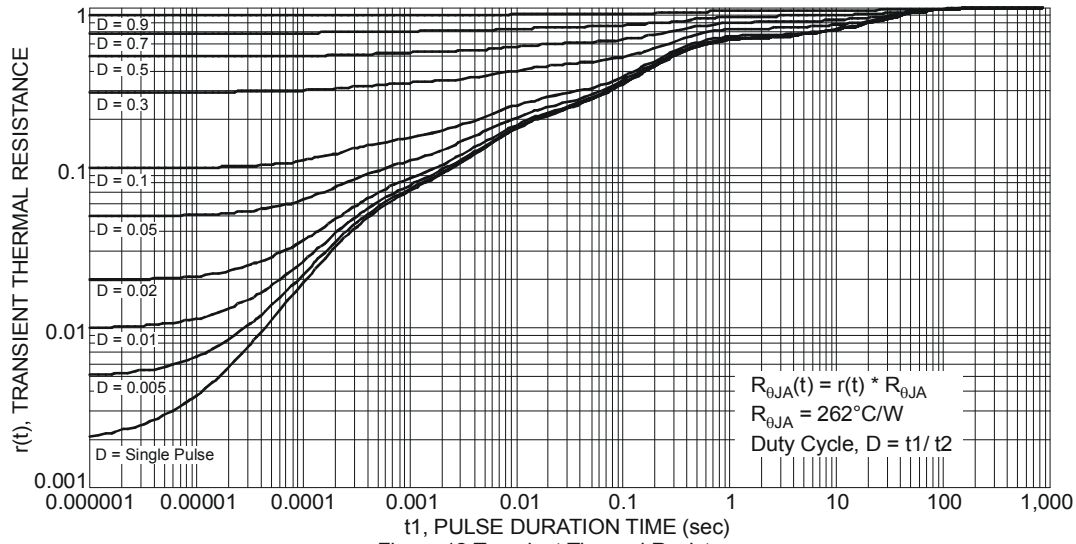


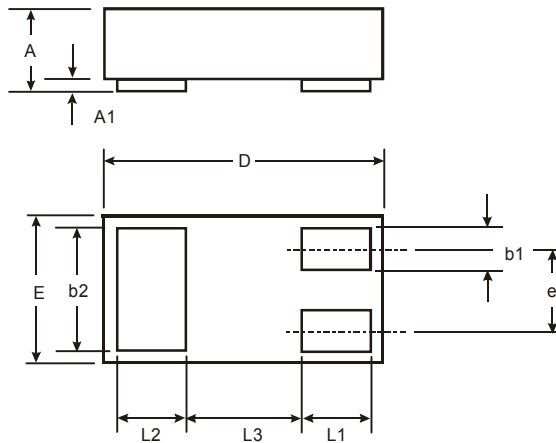
Figure 6 On-Resistance Variation with Temperature





## Package Outline Dimensions

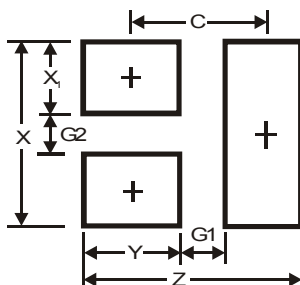
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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